

Power Resistor for Mounting onto a Heatsink Thick Film Technology

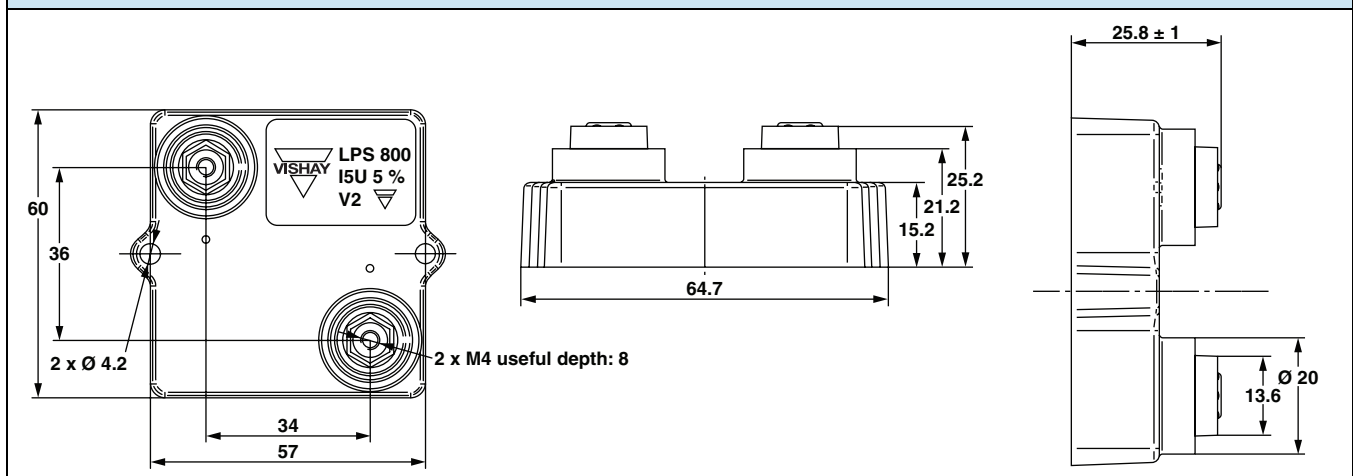


FEATURES

- 800 W at 85 °C bottom case temperature
- Wide resistance range: 0.3 Ω to 900 kΩ E24 series
- Non inductive
- Easy mounting
- Low thermal radiation of the case
- Compliant to RoHS directive 2002/95/EC


RoHS
COMPLIANT

DIMENSIONS in millimeters



Note

- Tolerances unless stated: ± 0.2 mm

MECHANICAL SPECIFICATIONS

Mechanical Protection	Insulated case UL 94 V-0
Resistive Element	Thick film
Substrate	Alumina
End Connections	Screws M4
Tightening Torque	
- On Connections	2 Nm
- On Heatsink	2 Nm
Maximum Torque	2.5 Nm
Weight	83 g ± 10 %

ENVIRONMENTAL SPECIFICATIONS

Temperature Range	- 55 °C to 175 °C
Climatic Category	55/175/56

ELECTRICAL SPECIFICATIONS

Resistance Range	0.3 Ω to 900 kΩ
Tolerances (Standard)	± 1 % to ± 10 %
Power Rating and Thermal Resistance	800 W at + 85 °C bottom case temperature $R_{TH(j-c)}$: 0.112 °C/W
Temperature Coefficient	$R \leq 1 U$: ± 500 ppm/°C $1 U < R \leq 10 U$: ± 300 ppm/°C $10 U < R$: ± 150 ppm/°C
Limiting Element Voltage U_L	5 kV
Dielectric Strength IEC 60115-1, 1 min, 10 mA max.	7 kV _{RMS} or 12 kV _{RMS}
Insulation Resistance	≥ 10 ⁴ MΩ
Inductance	≤ 0.1 μH
Critical Resistance	31.25 kΩ



PERFORMANCE		
TESTS	CONDITIONS	REQUIREMENTS
Momentary Overload	IEC 60115-1 1.5 x P _r /10 s U _{max.} ≤ U _L = 5000 V	± (0.25 % + 0.05 Ω)
Rapid Temperature Change	IEC 60115-1/IEC 60068-2-14 Test Na 50 cycles - 55 °C to + 175 °C	± (0.5 % + 0.05 Ω)
Load Life	IEC 60115-1 1000 h (90/30) P _r at 85 °C	± (0.5 % + 0.05 Ω)
Humidity (Steady State)	IEC 60115-1 56 days RH 95 %/40 °C	± (0.5 % + 0.05 Ω)
Vibration	MIL STD 202 Method 204 Cond. D (10 g; 5/500 Hz)	± (0.25 % + 0.05 Ω)
Climatic Sequence	IEC 60115-1 (55/175/56)	± (1 % + 0.05 Ω)

RECOMMENDATIONS FOR MOUNTING ONTO A HEATSINK

- Surfaces in contact must be carefully cleaned.
- The heatsink must have an acceptable flatness: From 0.05 mm to 0.1 mm/100 mm.
- Roughness of the heatsink must be around 6.3 μm. In order to improve thermal conductivity, surfaces in contact (alumina, heatsink) should be coated with a silicone grease (type SI 340 from Rhône-Poulenc or Dow 340 from Dow Corning) or a thermal film (type Q Pad II) easier and faster to install than the grease.
- The fastening of the resistor to the heatsink is under pressure control of two screws tightened at 2 Nm for full power availability.

Tightening Torque on Heatsink	LPS 800
	2 Nm

- The following accessories are supplied with each product: 2 screws CHC M4 * 25 class 8.8 and 2 M4 contact lock washers for heatsink mounting,
2 screws TH M4 * 6/6 and 2 M4 contact lock washers for connections.

CHOICE OF THE HEATSINK

The user must choose the heatsink according to the working conditions of the component (power, room temperature). Maximum working temperature must not exceed 175 °C. The dissipated power is simply calculated by the following ratio:

$$P = \frac{\Delta T}{[R_{TH(j-c)} + R_{TH(c-a)}]}$$

- P: Expressed in W
- ΔT: Difference between maximum working temperature and room temperature
- R_{TH(j-c)}: Thermal resistance value measured between resistive layer and outer side of the resistor. It is the thermal resistance of the component: (see specifications environmental paragraph).
- R_{TH(c-a)}: Thermal resistance value measured between outer side of the resistor and room temperature. It is the thermal resistance of the thermal interface, the heatsink (type, shape) and the quality of the fastening device.

Example:

R_{TH(c-a)} for LPS 800 power dissipation 180 W at + 50 °C room temperature.
 ΔT ≤ 175 °C - 50 °C = 125 °C
 $R_{TH(j-c)} + R_{TH(c-a)} = \frac{\Delta T}{P} = \frac{125}{180} = 0.69 \text{ °C/W}$
 R_{TH(j-c)} = 0.112 °C/W
 R_{TH(c-a)} = 0.69 °C/W - 0.112 °C/W = 0.578 °C/W



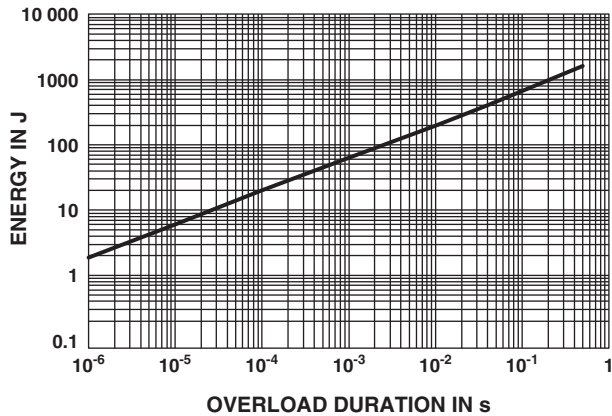
OVERLOADS

In any case the applied voltage must be lower than $U_L = 5000$ V.

Short time overload: $1.5 \times P_r/10$ s

Accidental overload: The values indicated on the following graph are applicable to resistors in air or mounted onto a heatsink.

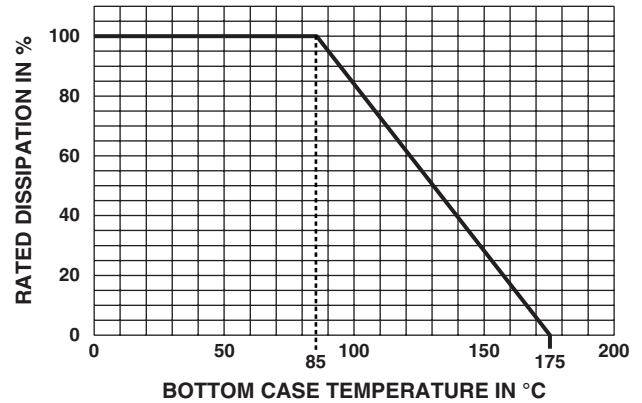
ENERGY CURVE



POWER RATING

The temperature of the case should be maintained within the limits specified in the following figure.

To optimize the thermal conduction, contacting surfaces should be coated with silicone grease or thermal film, and heatsink mounting screws tightened to 2 Nm.



MARKING

Series, style, ohmic value (in Ω), tolerance (in %), manufacturing date, Vishay Sfernice trademark.

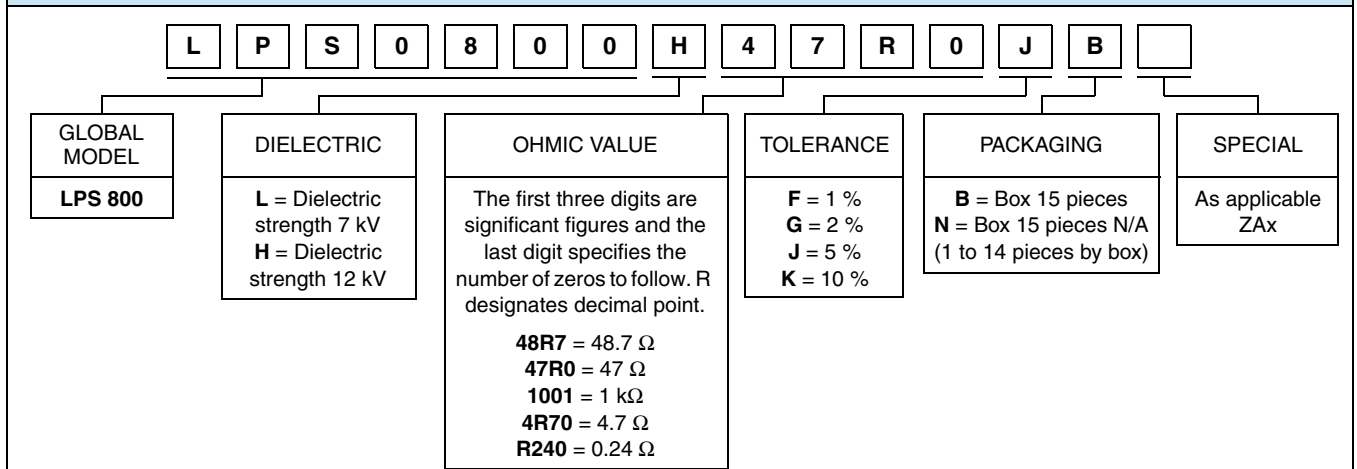
PACKAGING

Box of 15 units

ORDERING INFORMATION

LPS	800	100 kΩ	± 1 %	xxx	BO15	e
MODEL	STYLE	RESISTANCE VALUE	TOLERANCE	CUSTOM DESIGN Optional on request: Special TCR, shape etc.	PACKAGING	LEAD (Pb)-FREE
			± 1 % ± 2 % ± 5 % ± 10 %			

GLOBAL PART NUMBER INFORMATION





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